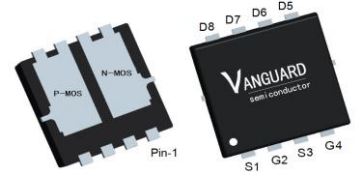


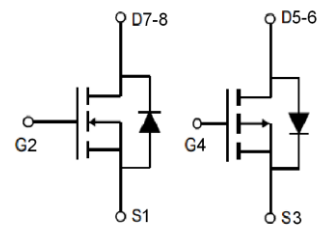
## Features

- N+P Channel
- Enhancement mode
- Very low on-resistance
- Fast Switching
- Pb-free lead plating; RoHS compliant

$V_{DS}$	30	-30	V
$R_{DS(on),TYP}@ V_{GS}=\pm 10V$	6.5	13	m $\Omega$
$R_{DS(on),TYP}@ V_{GS}=\pm 4.5V$	10	24	m $\Omega$
$I_D$	45	-35	A

**PDFN5x6**


Part ID	Package Type	Marking	Tape and reel information
VSP008C03MD	PDFN5x6	008C03MD	3000pcs/Reel



## Maximum ratings, at $T_A = 25^\circ\text{C}$ , unless otherwise specified

Symbol	Parameter	Rating		Unit	
		NMOS	PMOS		
$V_{(BR)DSS}$	Drain-Source breakdown voltage	30	-30	V	
$I_S$	Diode continuous forward current	$T_C = 25^\circ\text{C}$	45	-35	A
$I_D$	Continuous drain current@ $V_{GS}=\pm 10V$	$T_C = 25^\circ\text{C}$	45	-35	A
		$T_C = 100^\circ\text{C}$	29	-22	A
$I_{DM}$	Pulse drain current tested ①	$T_C = 25^\circ\text{C}$	180	-140	A
EAS	Avalanche energy, single pulsed ②		25	36	mJ
$P_D$	Maximum power dissipation	$T_C = 25^\circ\text{C}$	25	28	W
$V_{GS}$	Gate-Source voltage		$\pm 20$	$\pm 20$	V
$T_{STG} T_J$	Storage and operating temperature range		-55 to 150	-55 to 150	$^\circ\text{C}$

## Thermal Characteristics

Symbol	Parameter	Typical		Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	5	4.5	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	50	50	$^\circ\text{C/W}$

**N-Channel Electrical Characteristics**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	30	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current(T <sub>A</sub> =25°C)	V <sub>DS</sub> =30V,V <sub>GS</sub> =0V	--	--	1	μA
	Zero Gate Voltage Drain Current(T <sub>A</sub> =125°C)	V <sub>DS</sub> =30V,V <sub>GS</sub> =0V	--	--	100	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	1.0	1.9	2.5	V
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance ③	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	--	6.5	8	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =16A	--	10	12	mΩ
<b>Dynamic Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V,V <sub>GS</sub> =0V, f=1MHz	--	1140	--	pF
C <sub>oss</sub>	Output Capacitance		--	180	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	135	--	pF
R <sub>g</sub>	Gate Resistance	f=1MHz	--	2	--	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =15V,I <sub>D</sub> =20A, V <sub>GS</sub> =10V	--	22	--	nC
Q <sub>gs</sub>	Gate Source Charge		--	4.7	--	nC
Q <sub>gd</sub>	Gate Drain Charge		--	7	--	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn on Delay Time	V <sub>DD</sub> =15V, I <sub>D</sub> =20A, R <sub>G</sub> =3Ω, V <sub>GS</sub> =10V	--	8.5	--	nS
t <sub>r</sub>	Turn on Rise Time		--	4	--	nS
t <sub>d(off)</sub>	Turn Off Delay Time		-	19	--	nS
t <sub>f</sub>	Turn Off Fall Time		--	5.5	--	nS
<b>Source Drain Diode Characteristics</b>						
V <sub>SD</sub>	Forward on voltage	I <sub>SD</sub> =15A,V <sub>GS</sub> =0V	--	0.84	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	T <sub>J</sub> =25°C,I <sub>sd</sub> =20A, V <sub>GS</sub> =0V	--	10.7	--	nS
Q <sub>rr</sub>	Reverse Recovery Charge	di/dt=500A/μs	--	15.5	--	nC

**NOTE:**

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Limited by T<sub>Jmax</sub>, starting T<sub>J</sub> = 25°C, L = 0.5mH,R<sub>G</sub> = 25Ω, I<sub>AS</sub> = 10A, V<sub>GS</sub> =10V. Part not recommended for use above this value
- ③ Pulse width ≤ 300μs; duty cycle≤ 2%.

**P-Channel Electrical Characteristics**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-30	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current(T <sub>A</sub> =25°C)	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V	--	--	-1	μA
	Zero Gate Voltage Drain Current(T <sub>A</sub> =125°C)	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V	--	--	-100	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1.0	-1.9	-2.5	V
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance ③	V <sub>GS</sub> =-10V, I <sub>D</sub> =-20A	--	13	16	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-16A	--	24	28	mΩ
<b>Dynamic Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, f=1MHz	--	2605	--	pF
C <sub>oss</sub>	Output Capacitance		--	300	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	230	--	pF
R <sub>g</sub>	Gate Resistance	f=1MHz	--	3.3	--	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-15V, I <sub>D</sub> =-20A, V <sub>GS</sub> =-10V	--	44	--	nC
Q <sub>gs</sub>	Gate Source Charge		--	9	--	nC
Q <sub>gd</sub>	Gate Drain Charge		--	10.6	--	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn on Delay Time	V <sub>DD</sub> =-15V, I <sub>D</sub> =-20A, R <sub>G</sub> =3Ω, V <sub>GS</sub> =-10V	--	11.4	--	ns
t <sub>r</sub>	Turn on Rise Time		--	22	--	ns
t <sub>d(off)</sub>	Turn Off Delay Time		-	57	--	ns
t <sub>f</sub>	Turn Off Fall Time		--	32	--	ns
<b>Source Drain Diode Characteristics</b>						
V <sub>SD</sub>	Forward on voltage	I <sub>SD</sub> =-15A, V <sub>GS</sub> =0V	--	-0.9	-1.2	V
t <sub>rr</sub>	Reverse Recovery Time	T <sub>J</sub> =25°C, I <sub>sd</sub> =-20A, V <sub>GS</sub> =0V	--	27	--	nS
Q <sub>rr</sub>	Reverse Recovery Charge	di/dt=-500A/μs	--	77	--	nC

**NOTE:**

- ① Repetitive rating; pulse width limited by max. junction temperature.  
 ② Limited by T<sub>Jmax</sub>, starting T<sub>J</sub> = 25°C, L = 0.5mH, R<sub>G</sub> = 25Ω, I<sub>AS</sub> = -12A, V<sub>GS</sub> = -10V. Part not recommended for use above this value  
 ③ Pulse width ≤ 300μs; duty cycle ≤ 2%.



### N-Channel Typical Characteristics

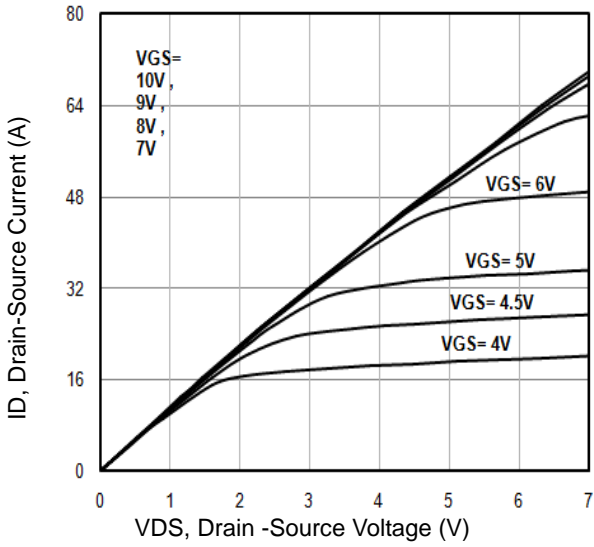


Fig1. Typical Output Characteristics

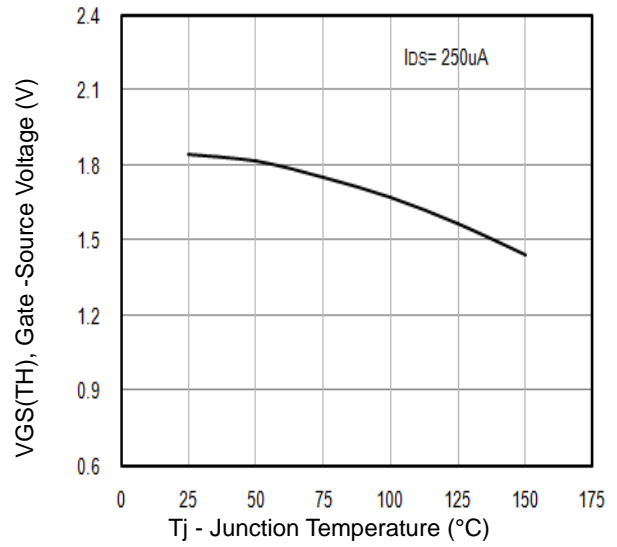


Fig2.  $V_{GS(TH)}$  Gate-Source Voltage Vs.  $T_j$

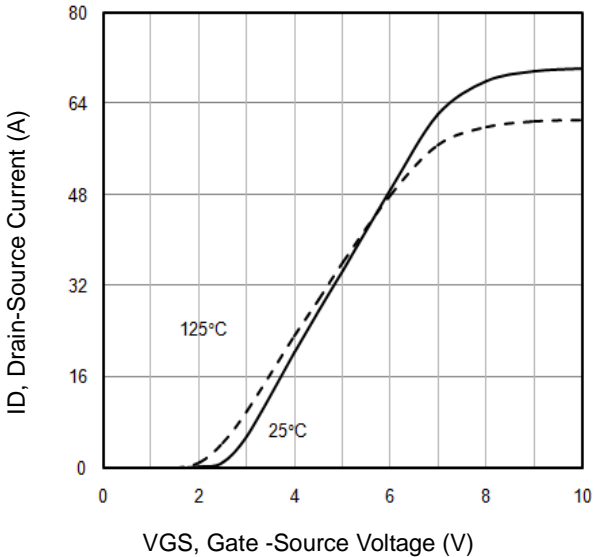


Fig3. Typical Transfer Characteristics

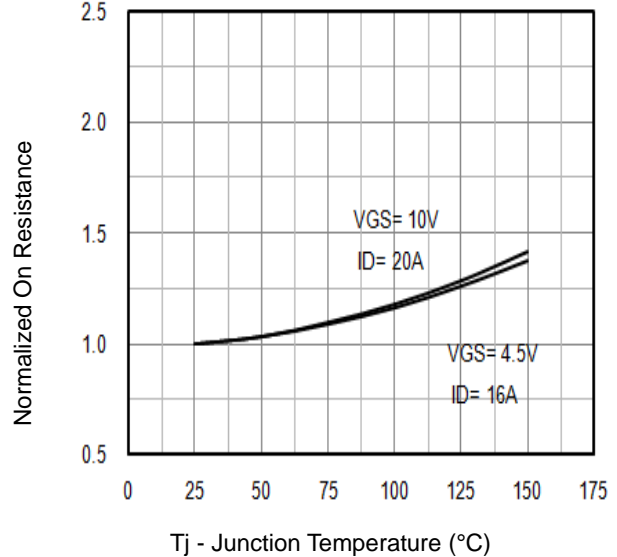


Fig4. Normalized On-Resistance Vs.  $T_j$

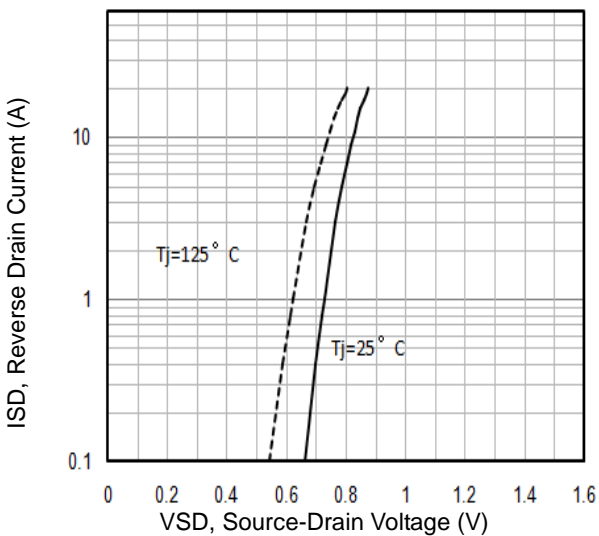


Fig5. Typical Source-Drain Diode Forward Voltage

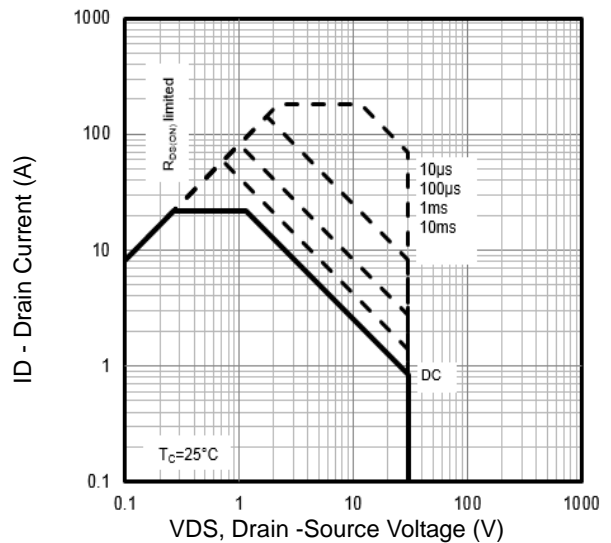


Fig6. Maximum Safe Operating Area

### N-Channel Typical Characteristics

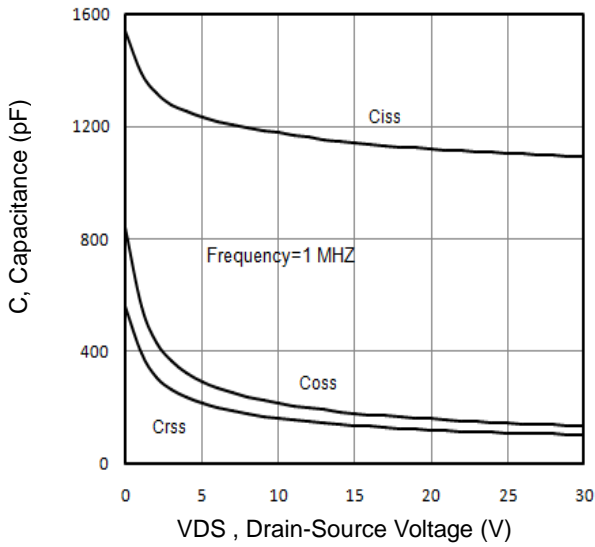


Fig7. Typical Capacitance Vs.Drain-Source Voltage

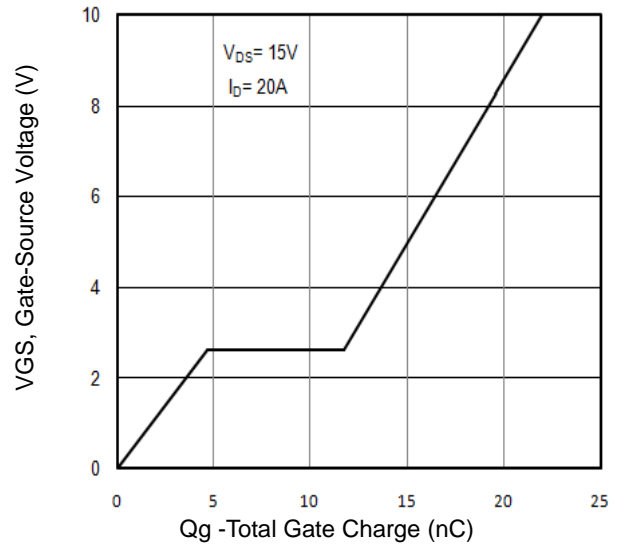


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

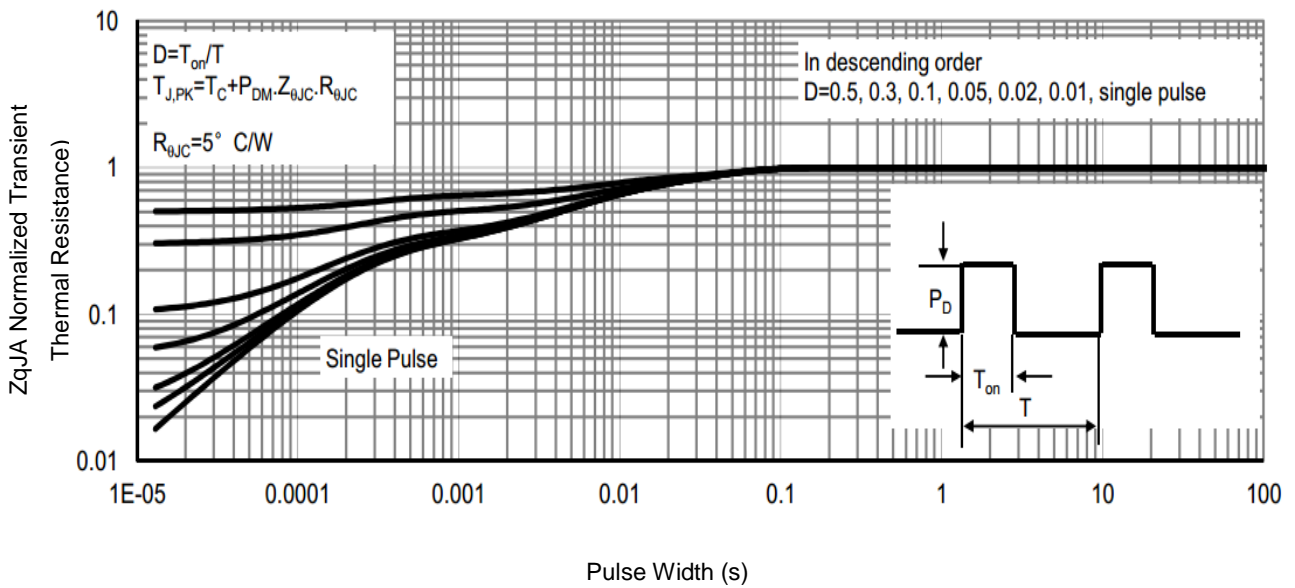


Fig 9 .Normalized Maximum Transient Thermal Impedance

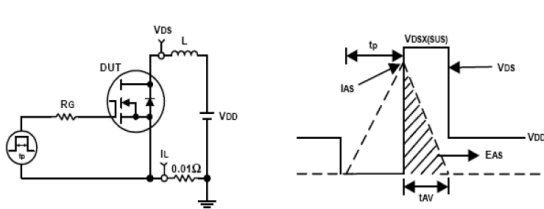


Fig10. Unclamped Inductive Test Circuit and waveforms

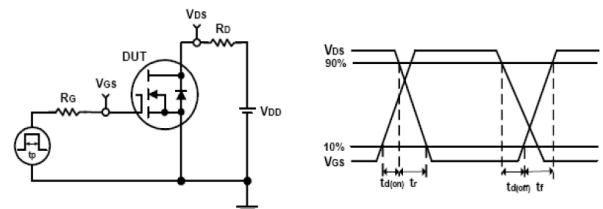


Fig11. Switching Time Test Circuit and waveforms



### P-Channel Typical Characteristics

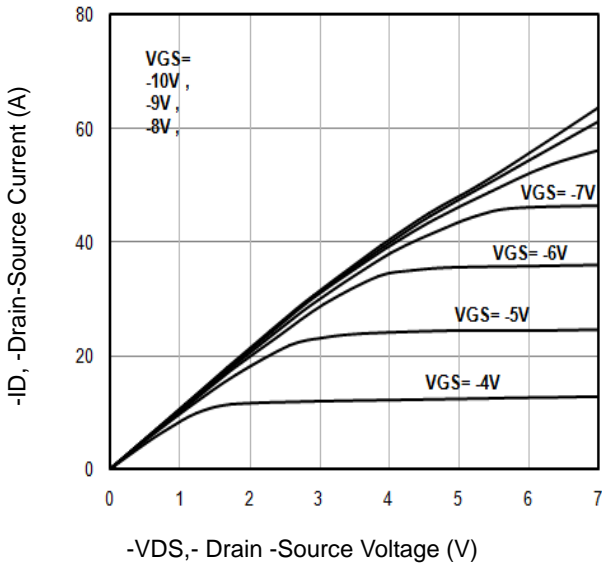


Fig1. Typical Output Characteristics

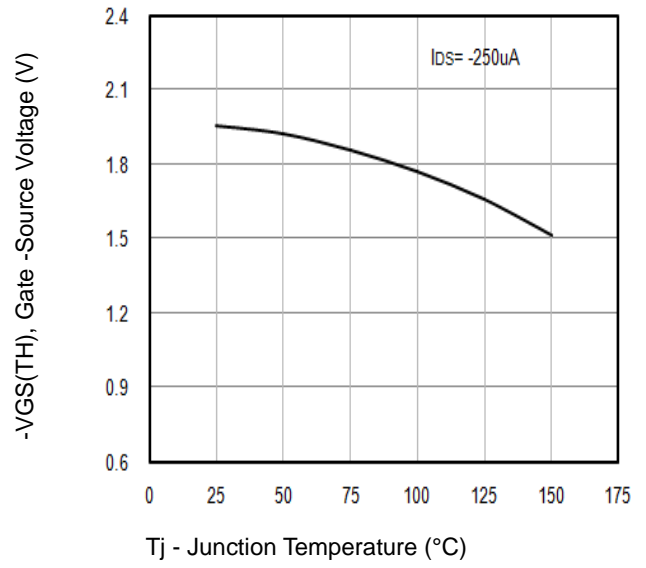


Fig2.  $-V_{GS(TH)}$  Gate -Source Voltage Vs.  $T_j$

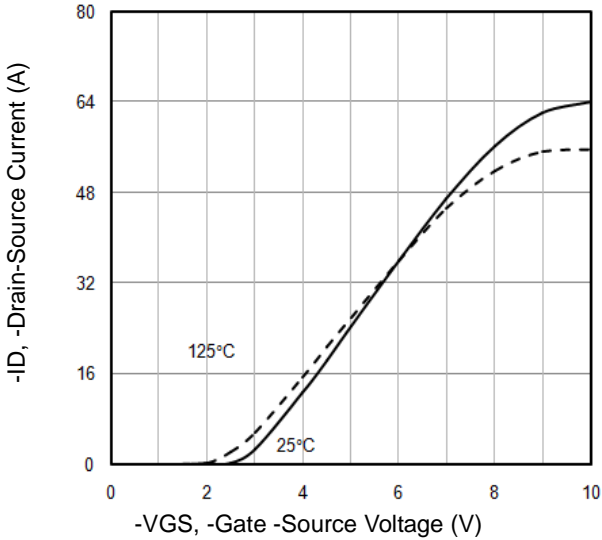


Fig3. Typical Transfer Characteristics

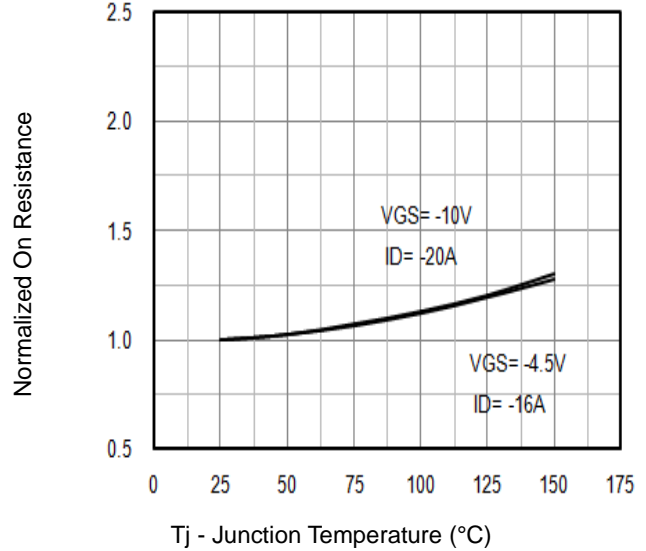


Fig4. Normalized On-Resistance Vs.  $T_j$

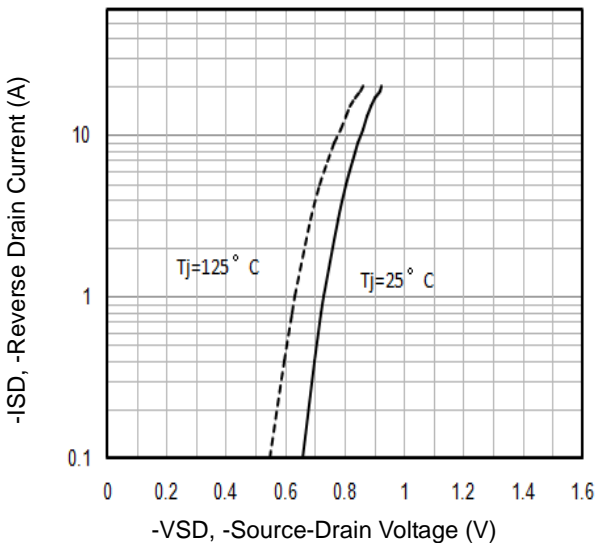


Fig5. Typical Source-Drain Diode Forward Voltage

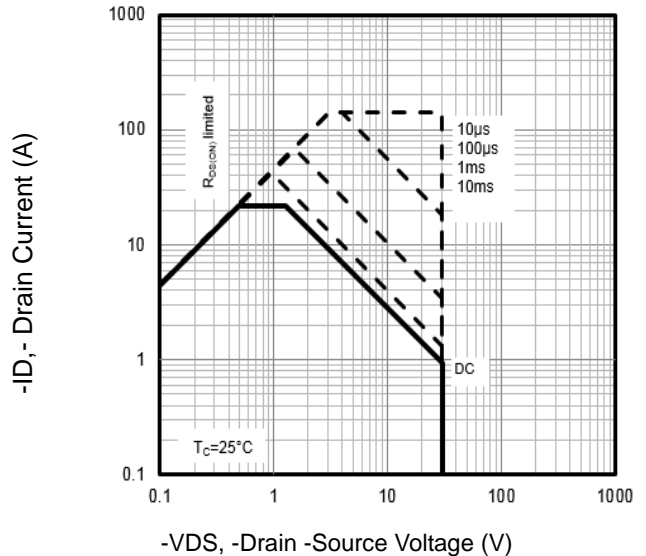


Fig6. Maximum Safe Operating Area

P-Channel Typical Characteristics

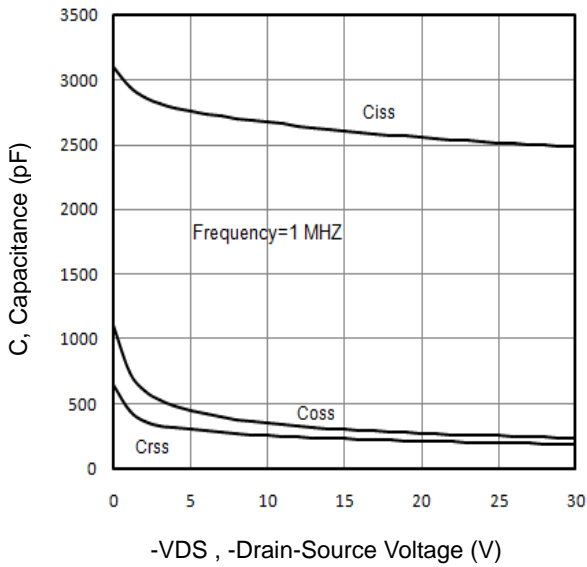


Fig7. Typical Capacitance Vs.Drain-Source Voltage

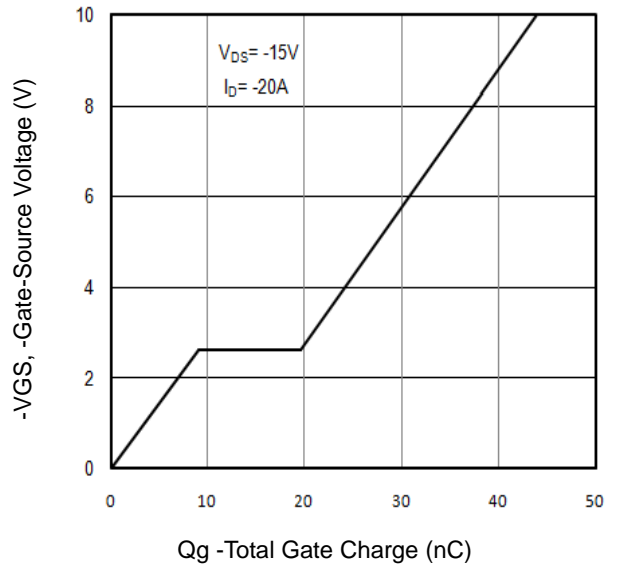


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

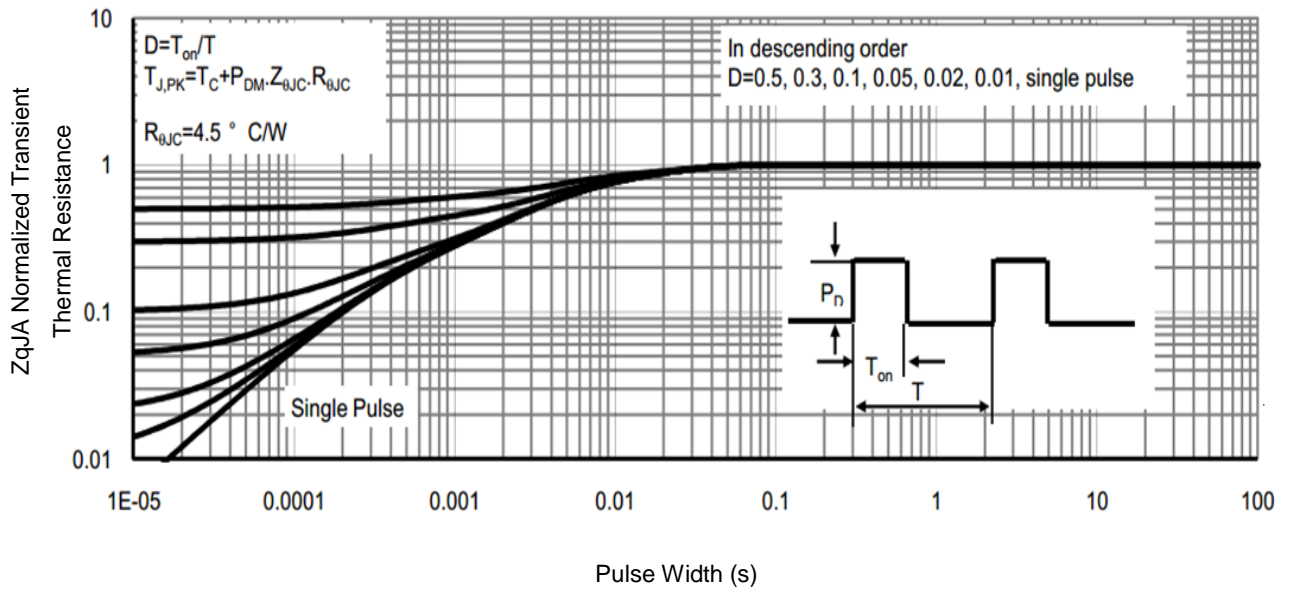


Fig9. Normalized Maximum Transient Thermal Impedance

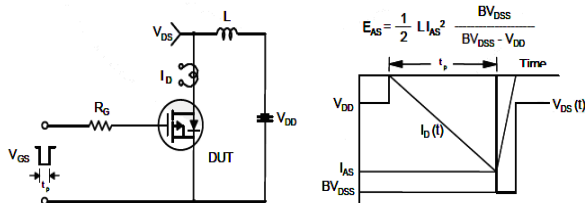


Fig10. Unclamped Inductive Test Circuit and Waveforms

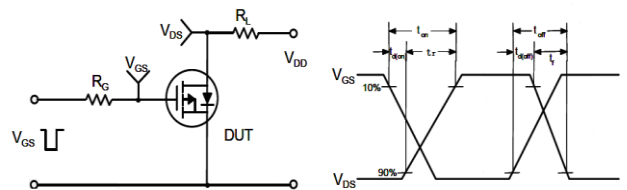
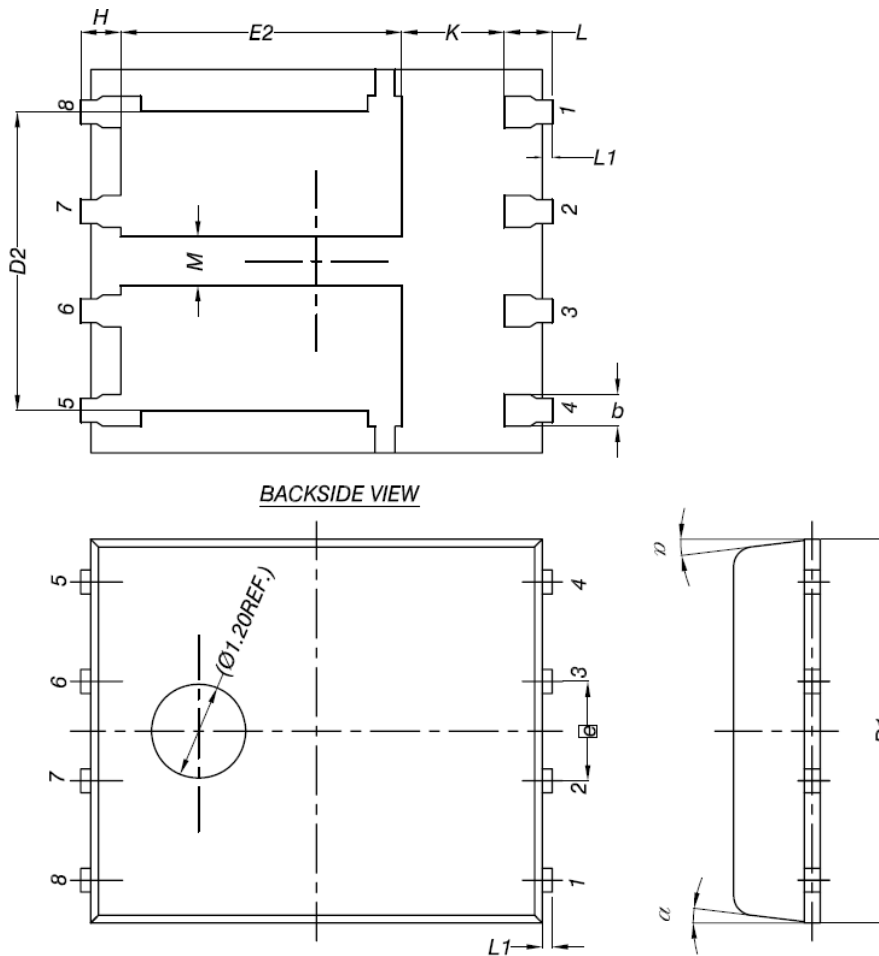


Fig11. Switching Time Test Circuit and waveforms



PDFN5x6 Package Outline Data



DIMENSIONS ( unit : mm )

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.00	1.10	e	1.27 BSC		
b	0.33	0.41	0.51	H	0.41	0.51	0.61
C	0.20	0.25	0.30	K	1.10	--	--
D1	4.80	4.90	5.00	L	0.51	0.61	0.71
D2	3.61	3.81	3.96	L1	0.06	0.13	0.20
E	5.90	6.00	6.10	M	0.50	--	--
E1	5.70	5.75	5.80	$\alpha$	0°	--	12°
E2	3.38	3.58	3.78				

Customer Service

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